

PATENTS ABSTRACTS OF JAPAN

E-876 January 22, 1990 Vol. 14/No. 32

(54) METHOD AND APPARATUS FOR WAFER POLISHING no. JP

(11) 1-268032 (A) (43) 25.10.1989 (19) JP

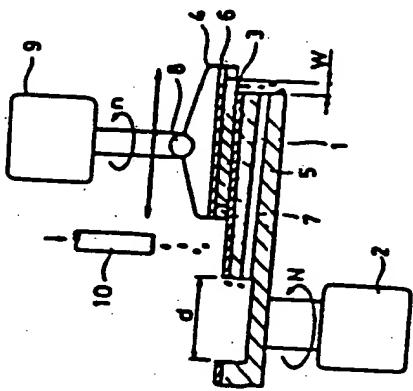
(21) Appl. No. 63-95505 (22) 20.4.1988

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(1) Int. Cl. H01L21/3047

PURPOSE: To enable accurately polish a wafer into plane form, by polishing the wafer held in a polishing chuck with a part thereof sticking out from a polishing surface plate or a polishing cloth.

CONSTITUTION: Each polishing chuck 4 holds one semiconductor wafer 5, which is polished with a part thereof sticking out from a polishing surface plate 1 or a polishing cloth 3. For example, the semiconductor wafer 5 to be polished is held by the polishing chuck 4 by vacuum absorption or any other means, rotating the polishing chuck 4 with a motor 9 forces the semiconductor wafer 5 to rotate together with the polishing chuck 4 at a rotating speed n and presses the wafer 5 on the polishing cloth 3 on the polishing surface plate 1 and presses this state rotates together with the polishing chuck 4 at a rotating speed n in plate 1 and is polished by the friction between said wafer and the polishing surface cloth 3, with a part thereof sticking out from the polishing cloth 3 in the inside and outside of the polishing surface plate 1.



LEGENDE zu den Bibliographiefelden

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| (54) Titel der Patentanmeldung | (54) Title of Patent Application |
| (11) Nummer der JP-A2 Veröffentlichung | (11) Number of JP-A2 Publication |
| (21) Aktenzeichen der JP-Anmeldung | (21) File Reference of JP Application |
| (43) Veröffentlichungstag | (43) Publication Date |
| (71) Anmelder | (71) Applicant |
| (72) Erfinder | (72) Inventor |
| (52) Japanische Patentklassifikation | (52) Japanese Patent Classification |
| (51) Internationale Patentklassifikation | (51) International Patent Classification |